

Approval Sheet

Products	Dielectric Chip Antenna			
Customer	UMID			
Model		Metallifer		
Customer CODE				
Supplier		PARTRON		
Supplier CODE		ACS2450ICAMEB		
	By designed	By checked	By approved	
CLIPCOM				
	By designed	By checked	By approved	
PARTRON	12(6)	String	為人	
	Research 5 Team	Quality Assurance	Laboratory	
	Chanik.Jeon	Nam-Sik.Min	Byoung-Jun.Yim	
	02 / 09	02 / 09		

2009. 02. 09



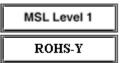
22-6 Seokwoo-dong, Hwaseong-si, Gyeonggi-do, Korea 455-300

Te I: 82-31-201-7870~6 Fax: 82-31-201-7800 www.partron.co.kr



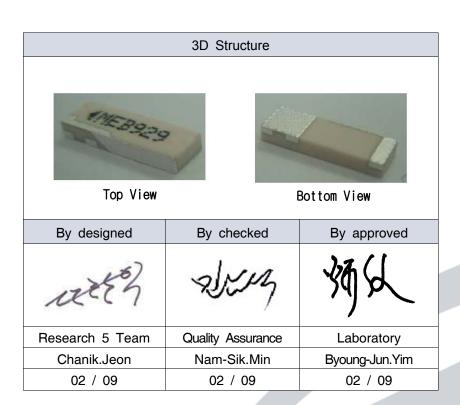






SPECIFICATION

MODEL: ACS2450ICAMEB



2009. 02. 09



22-6 Seokwoo-dong, Hwaseong-si, Gyeonggi-do, Korea 455-300

Tel: 82-31-201-7870~6 Fax: 82-31-201-7800 www.partron.co.kr

ACS2450ICAMEB



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1. Revision

Revision No	Originator	Description of changes	Date of changes
Ver 1.0	Chanik.Jeon	Issued	2009.02.09

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2. Summary of Parts

- This product is the internal dielectric chip antenna of radio communication, forms the pattern with Ag paste on the brick of dielectric block and materializes the characteristics

Туре	Only Bulk Ceramic				
Material	Dielectric Block	Mg₂SiO₄(Magnesium Silicate)			
Material	Electrode Paste	Ag			
	$W = 3.0 \pm 0.1$				
Size[mm]	$L = 9.0\pm0.1$	Ag Paste			
	$T = 1.2 \pm 0.1$	W			
Flatness Level	0.04	T BOOD			
MSL Level	MSL Level 1	Dielectric			
ESD Level	More than 15 kV (HBM CLASS 3B)	Top- Side View Bottom Side View			
Version	Revision 1.0				

3. Critical to Quality (

- The following list is specified as the emphasis management list and managed.

CTQ ITEM	Specification Reason	
Shape weight, size Shape weight and size determines the electric block size after plastic and the dielectric block size effects the level of detail for the printing.		
Plastic Size	The size after plastic effects the level of detail for the printing.	
Printing Size	The level of detail for printing size is an essential list of the BT antenna.	

CTF ITEM 🐟	Specification Reason
Single Element measurement SWR	An important Parameter classifying the electrical characteristics.

- require attention for the following list.

ITEM	Content
Keeping	Sealing tightly when keeping for a long time.
Action	Maybe characteristics changes when changing any design.

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4. Electrical Characteristics

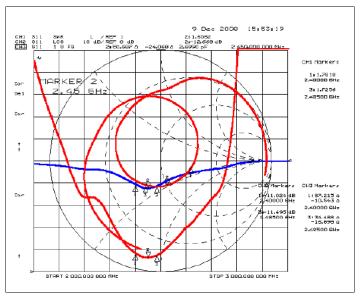
4.1 Set Condition

ITEM				SPEC		
Frequency Range [MHz]				2400 ~ 2485		
	SWR	[Max]		3.0 : 1 [Typ 2.0:1]		
Input Impedance [Ω]				50 Ohm		
	Polariz	ation		Linear		
	Total Gair	n (Peak / /	Avg) [dBi]	-0.9 / -6.6		
		Thete	Peak	-1.38		
	A = imposith	Theta	Average	-5.77		
	Azimuth		Peak	-1.13		
		Phi	Average	-6.58		
		1	Peak	-2.99		
Gain[dBi]		Theta	Average	-7.74		
	Elevation 1	Phi	Peak	-2.17		
			Average	-6.94		
		T	Peak	-2.45		
	El c	Theta	Average	-7.78		
	Elevation 2	Di :	Peak	-0.83		
	Phi		Average	-5.23		

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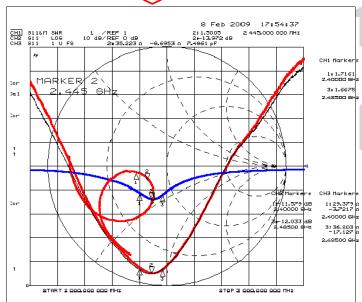
4.2 S11 Graph of Set Condition



4.3 Test Fixture Condition

ITEM	SPEC	
Frequency Range [MHz]	2400 ~ 2485	
Lower frequency(2400MHz) SWR [Min~Max]	3.0 : 1(Typ 2.0 :1)	
Upper frequency(2485MHz) SWR [Min~Max]	3.0 : 1(Typ 2.0 :1)	

4.4 S11 Graph of Test Fixture Condition

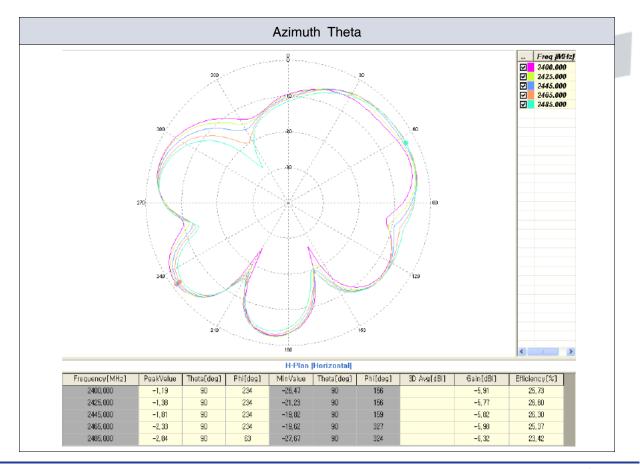


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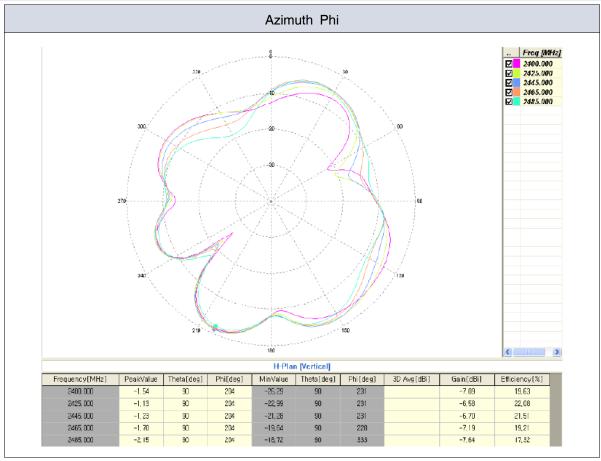
4.5 Radiation Pattern

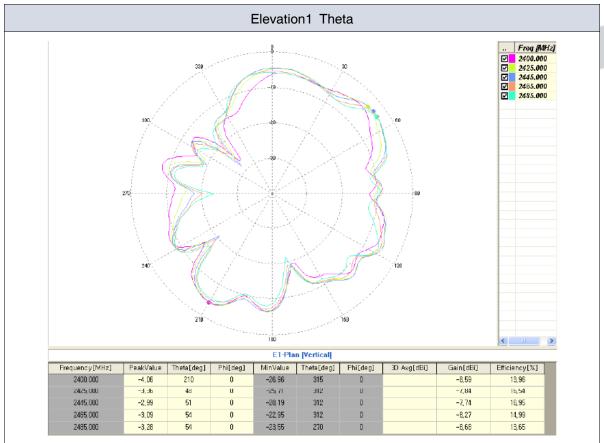
Azimuth Plane	Elevation1 Plane	Elevation2 Plane	
270° — 90°	90° 180°	270° — 90° — 90° — 180°	
Theta	Vertical field of measured plane		
Phi	Horizontal field of measured plane		



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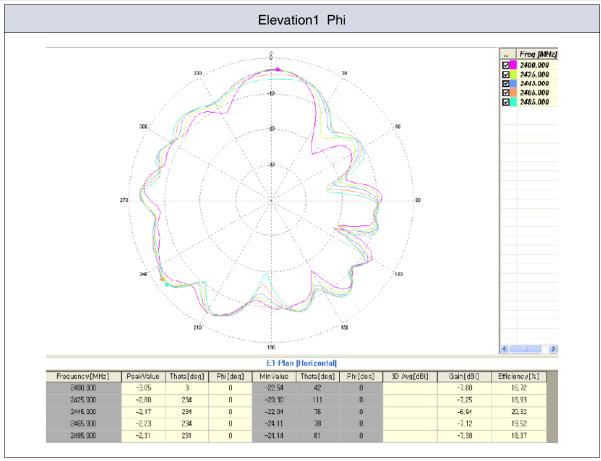


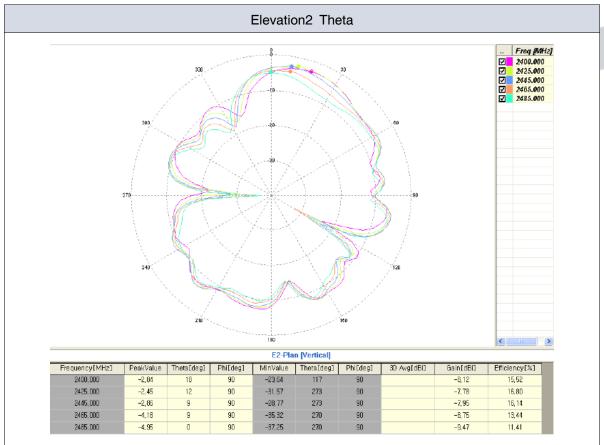




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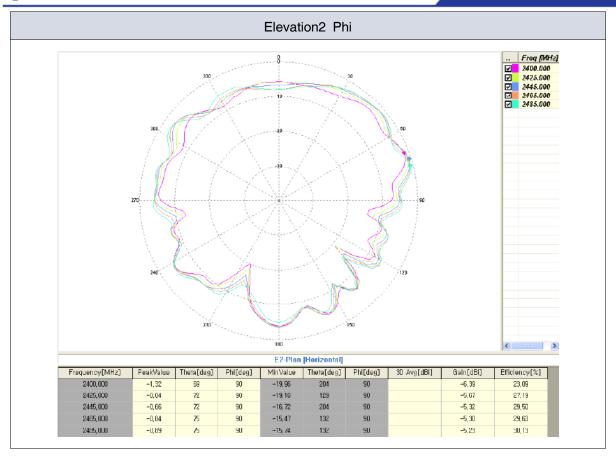






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5. Measurement Process

5.1 SWR/Return loss

Use Network Analyzer when measuring SWR/Return loss and selecting standard SPL, Use automatic inspection equipment when selecting superior and inferior goods.

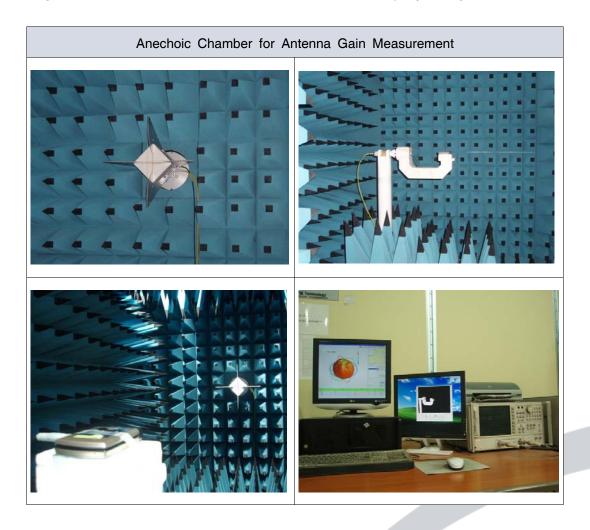
	Set Condition	Test Fixture Condition	
Network Analyzer	Agilent HP8753D	Agilent HP8753D or Advantest R3765CH	
Cable	RF cable(300mm)	RF cable(300mm)	
Test condition		CLUCK CCCCC CCCCC CCCCC CCCCCC CCCCCC CCCCCC	

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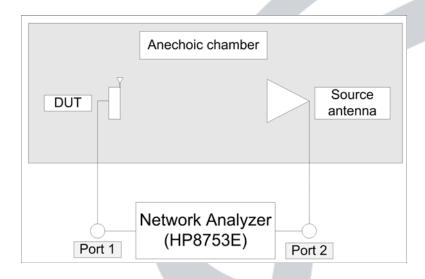


5.2 Gain

Antenna gain is measured in the Anechoic Chamber of this company, using set above of 4.1 list.



5.3 Gain test block diagram

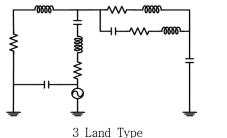


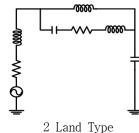
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6. Internal Block Diagram

This product is made of the dielectric block and RF part materialized the characteristics by structural change of Ag pattern on the brick of dielectric block and conditioning value of the structural equivalent circuit.

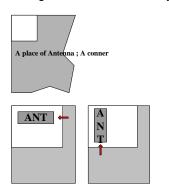




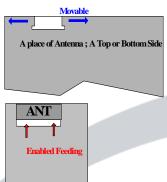
7. Basis Action / Application Note

This product is the internal dielectric chip antenna of radio communication, coverts the electric signal advanced along by transmission line into free space wave.

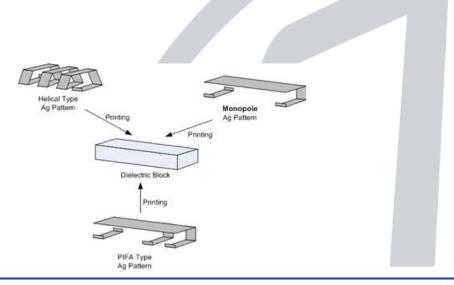
This product will be mounted wherever you want and the design is revised by mount condition. But require attention to select the mount position, because this product is the radiation part and changed characteristics by boundary condition,







As the following, this product is easy to revise the various types for the boundary condition.



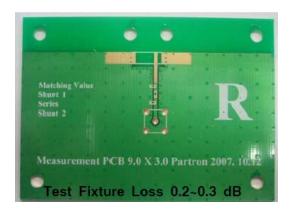
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8. Measurement Jig SPEC

8.1 Test Fixture And GROUND Condition

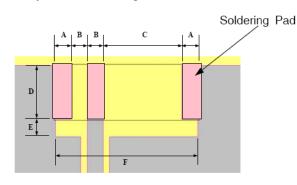




※ Ev B'd and Test Fixture Jig is the same

(Contact way of Ev B'd is soldering, Test Fixture is copper contact way)

8.2 PCB Layout & Soldering Pad Dimension



Copper Non-Copper

Top Layout

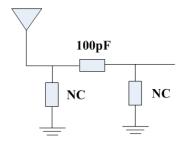
Bottom Pattern

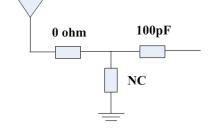
Parameter	Α	В	С	D	E	F	G
Value[mm]	1.1	1.0	5.0	3.2	1.0	9.2	4.2

Unit; mm

Unless specified tolerances are ±0.1

8.3 Matching Circuit And Reference Value





π Matching

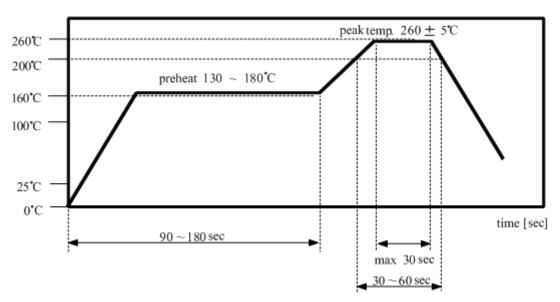
T Matching

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9. REFLOW PROFILE

9.1 Reflow Soldering

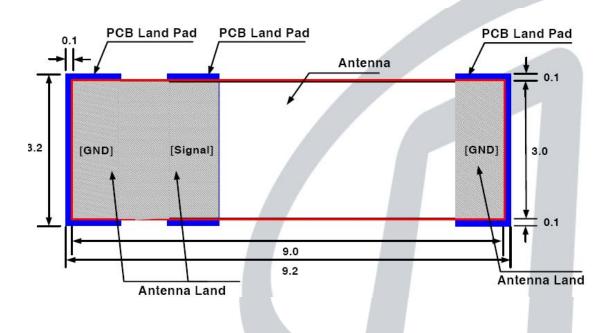


9.2 Manual Soldering

Soldering Temperature : 340 $^{\circ}\text{C}\pm5\,^{\circ}\text{C}$, 5sec max per each terminal

9.3 PCB Pattern Design

As the following, the PCB land pattern lays out 0.1mm outside land pattern of antenna more than indicated antenna land dimension



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10. Primary Inspection List

Item	Electrical Chara	Size [mm]				
0, 1	VSWR	3.0 MAX	W 00:04	1.00.04	T 40004	
Standard	2400 MHz	2485 MHz	W=3.0±0.1		I=1.2±0.1	
1	1.71	1.66	3.03	9.02	1.21	
2	1.64	1.73	3.02	9.01	1.22	
3	1.64	1.72	3.02	9.02	1.22	
4	1.67	1.71	3.01	9.01	1.21	
5	1.65	1.73	3.02	8.99	1.24	
6	1.59	1.78	3.04	9.00	1.23	
7	1.77	1.59	3.01	9.03	1.22	
8	1.57	1.77	3.01	9.00	1.23	
9	1.57	1.80	3.04	9.02	1.23	
10	1.63	1.73	3.03	9.02	1.24	
11	1.65	1.78	3.02 9.01		1.21	
12	1.62	1.71	3.02 9.00		1.22	
13	1.58	1.78	3.04 8.99		1.21	
14	1.62	1.77	3.01	9.01	1.23	
15	1.70	1.64	3.01	9.01	1.24	
16	1.58	1.72	3.02	9.00	1.23	
17	1.58	1.74	3.01	9.01	1.22	
18	1.62	1.75	3.04	9.00	1.22	
19	1.65	1.71	3.03	9.02	1.21	
20	1.58	1.79	3.02	9.01	1.21	
Min	1.57	1.59	3.01	8.99	1.21	
Max	1.77	1.60	3.04	9.03	1.24	
Х	1.63	1.73	3.02	9.01	1.22	
σ	0.05	0.05	0.01	0.01	0.01	
Cpk	8.53	7.86	2.28	2.79	2.38	
Decision	ok	ok	ok	ok	ok	

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11. Reliability Condition

11.1 Environment Test

ITEM	TEST CONDITION	LIMIT
High Temperature Action	85℃±3℃, 1hr	
High Temperature Resistance	+85℃±3℃, 120hr±2hr	
Low Temperature Action	-40℃±3℃, 1hr	After test, Must meet the
Low Temperature Resistance	-40℃±3℃, 120hr±2hr	characteristics spec of 4.4 list
Humidity Action	+85±3℃, RH85%	
Humidity Resistance	+85±3℃, RH85%, 120hr±2hr	

11.2 Thermal shock test , Reflow test

ITEM	TEST CONDITION	LIMIT
	condition : -40 $^{\circ}$ ±3 $^{\circ}$ /1min \leftrightarrow +85 $^{\circ}$ ±3 $^{\circ}$ /1min	
Thermal shock	Test Cycle: 32 cycle	After test, Must meet the
	Temperature change time : within 5 min	characteristics spec of
Reflow	Pre Heating : 200±5℃, 30~60 sec	4.4 list
Reliow	Peak Heating : 260℃±5℃, 30sec Max	

11.3 Mechanical Test

ITEM	TEST CONDITION	LIMIT
Vibration	Freq : 10~500Hz , Acceleration : 10 \times 9.8% (G) Sweep time : 15 min , X.Y.Z each 5 times	After test, Must meet the
Drop	18 times free fall Using the drop jig 152cm high Jig : 120g±20g Plastic Jig Bottom : Concrete or Iron	characteristics spec of 4.4 list

11.4 MSL LEVEL Test

1) JEDEC J-STD-020C Test

	F	Floor Life	Soak Requirements			
	Time	Conditions	Time	Conditions		
1	Unlimited	= < 30℃/85%RH	168+5/-0	= < 85℃/85%RH		

2) Test Condition

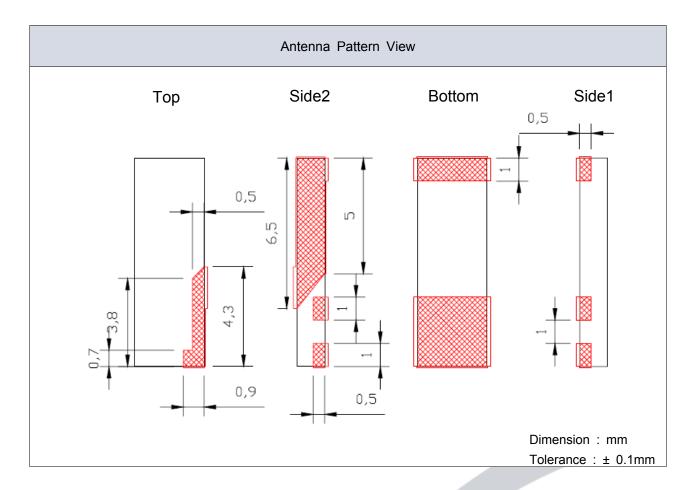
ITEM	Conditon	LIMIT	
Soak Requirements	After leaving +85±3℃, RH85% 2 times Reflow without aging	168hr±2hr	After test, Must meet the characteristics spec of 4.4 list

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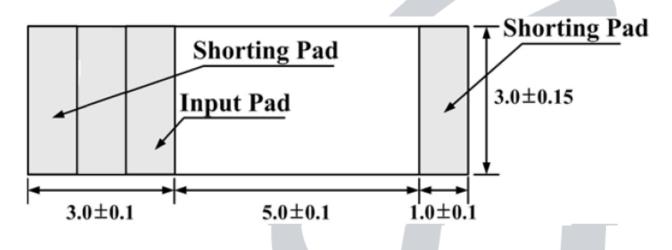


12. Mechanical Characteristics

12.1 Antenna Pattern Dimension



12.2 Pin name



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12.3 Lot number notation

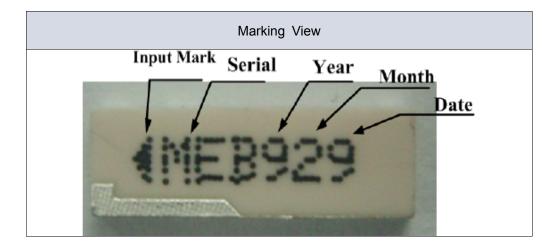
9 1 1 (1) (2) (3)

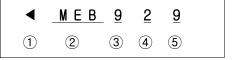
① Year : 9 - 2009 ····

2 Month: 1 - January, 2 - February · · 9 - September, A - October, B - November · ·

③ Date : 1 - 1st , 2 - 2nd ···· A - 10th, B - 11th ····

12.4 Marking





- 1 Input Signal
- ② Serial

③ Year : 1 - 2001, 2 - 2002, ···· 9 - 2009 ····

4 Month: 1 - January, 2 - February · · 9 - September, A - October, B - November · ·

⑤ Date : 1 - 1st , 2 - 2nd · · · · A - 10th, B - 11th · · · ·

12.5 Marking type

Ink marking - Using Black Ink

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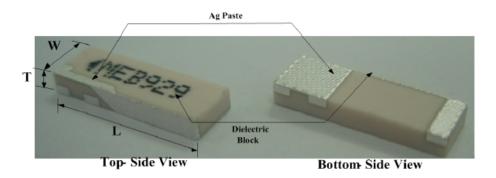


13. Structure and Material

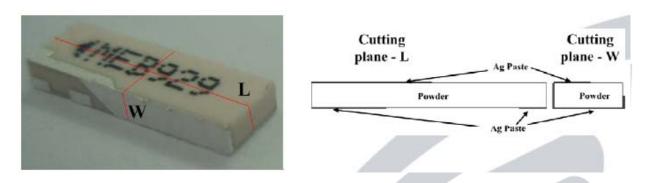
13.1 materialization method

Chip antenna forms the pattern with Ag paste on the brick of dielectric block and materializes the characteristics

13.2 Struture



13.3 Internal cross section



13.4 Material

ITEM	Material	Maker	Printing pattern SPEC
Dielectric Block	Powder	Fuji	
PATTERN	Ag Paste	Metech	Thickness: TYP 10/4m
PAD	Ag paste	Metech	Thickness: Min 10 m (TYP 16~20 m)

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14. Attention

14.1 Temperature Condition

	Range of Temperature	Unit
Application temperature	-40 ~ +85	$^{\circ}$
Keeping temperature	-40 ∼ +85	°C

14.2 Temperature Test Condition

	Condition	Range of Temperature
Application temperature	Low	24hr normal action at -75℃
Application temperature	High	24hr normal action at +150 ℃
Vacaina tamparatura	Low	normal action when left for 1000hr at -75℃
Keeping temperature	High	normal action when left for 1000hr at +85℃



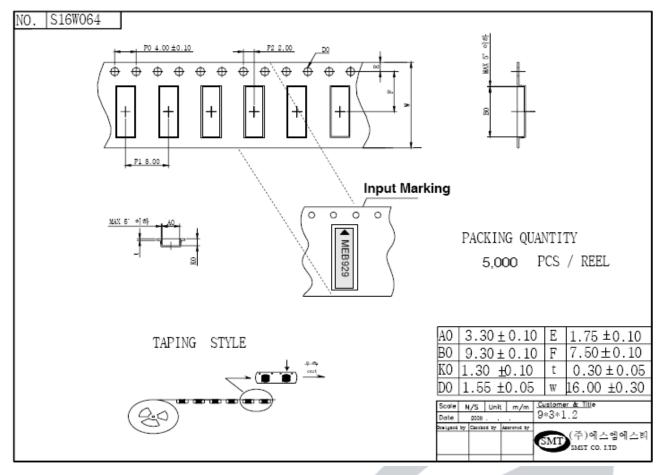
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15. Packing

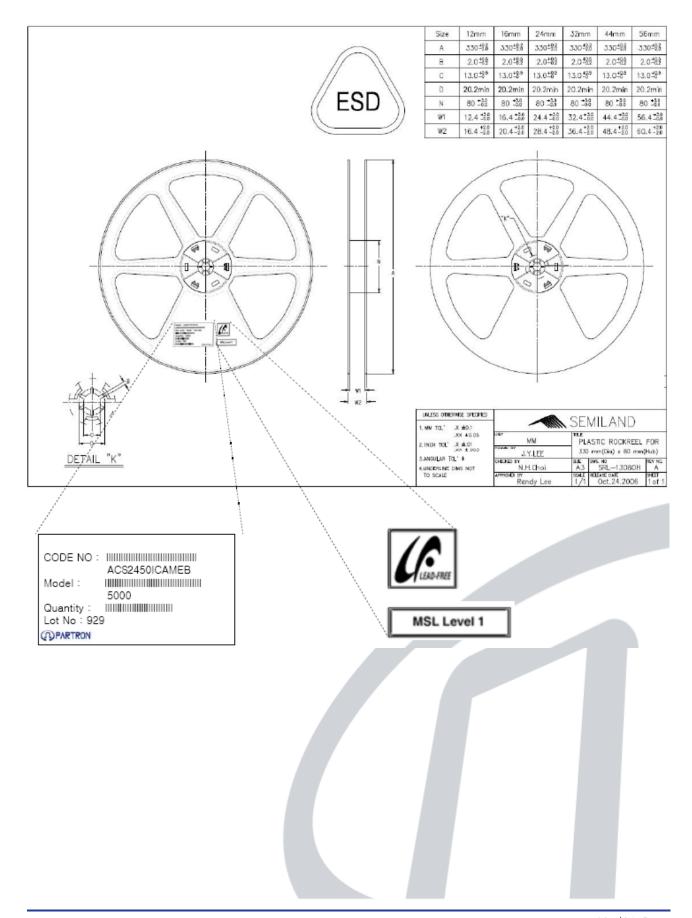
15.1 Carrier/Reel

ITEM	Material	Surface Resistance	electrostatic emission	Packing method
Carrier tape	A-PET	Typical 10 ⁸ Ω	10V MAX	Heat proce
Cover tape	PET	Typical 10 ⁸ Ω	30V MAX	Heat press
Reel	PS	Typical 10 ⁸ Ω	30V MAX	-



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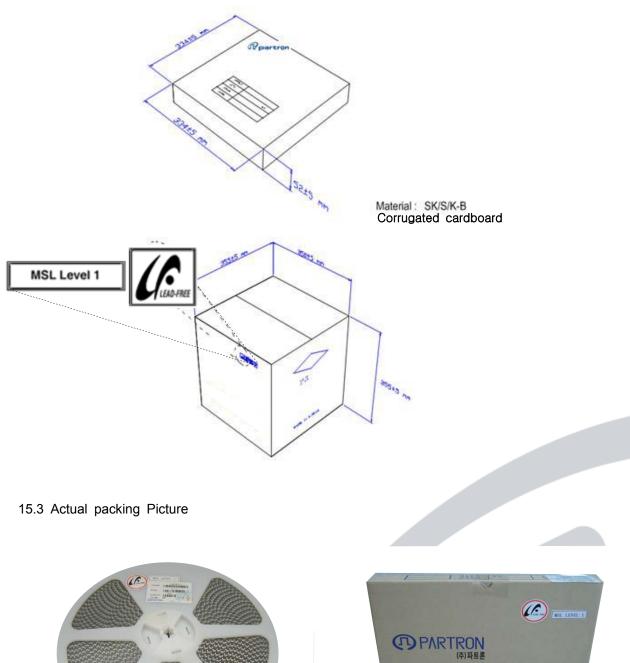




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15.2 BOX



Ree1



Internal Box

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External Box

CODE NO:

MODEL:

ACS2450 | CAMEB

QUANTITY: 30000

DATE: 929

PARTRON.

MSL LEVEL 1

FROM PARTRON.CO.LTD SEOKWOO.DONG 22-6 HWASEONG - SI GYEONGGI - DO 445-170.KOREA



CODE NO:

MODEL: ACS2450 I CAMEB

DATE: 2009/02/09

LOT NO: 929

CHIP ANT

Ppartron

Reel / Internal Box label

External Box label





16. Process Control

	Produc	t	ls	sued/Revisio	n	Process Control				Record	By designed	By check	ked By	approved
СН	IP ANTE	ENNA	lssue Revise							PRCP-COC	11			
Input	FLOW	CHART	Process		Manag	gement of Facto	ors			N	lanagement of qua	lity		
Materials	prepar ation	Main Process	name	Equipment Name	Checked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action
Ceramic POWDER		\Diamond	Import Inspection						shrinking rate permittivity	refer to Guide Sheet	Micrometer Network	10ea/L0T	C/sheet	Return
POWDER lubricant			powder	Mixer					mixing	POWDER lubricant	Scale	PER MIXING	-	Exhaust
			Shaping	Press	pressure Mold Condition	refer to Guide Sheet	Per LOT 1/day	parameter C/SHEET	dimension weight density aspect	refer to Guide Sheet	Micrometer scale Calculated Visual	5/100EA 10ea/lot	LOT CARD	Exhaust
			Plasticity	Plasticity Hole	SETTER Outside Temperature PROFILE	refer to Guide Sheet	all 2/day 1/month	C/sheet						
		\Diamond	Block						wide length shape	refer to Guide Sheet	Micrometer Calipers Visual Inspection	20ea/L0T 20ea/L0T all	C/sheet	Exhaust
AG PASTE			SIDE1 PAD Printing	Printer screen	Squeeze velocity/presur SNAP	refer to Guide Sheet	1/day	-	PATTERN Dimension aspect	refer to Guide Sheet	Microscope	10ea/3Jig	c/sheet	Rework
			Dry	Dryer Dry Jig	Temperature Belt speed	0	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework

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Product CHIP ANTENNA			Issued Revised		06	Process Control				Record	By designed	By chec	ked By	approved
	FLOW CHART			00.04.		ment of Factor	S			N	Management of qual	ity		
Input Materials	prepar Mai	n	Process - name	Equipment Name	Checked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action
AG PASTE			SIDE 2 PAD rinting	Printer screen	Squeeze velocity/presure SNAP	refer to Guide Sheet	1/day	-	PATTERN Dimension aspect	refer to Guide Sheet	Microscope	10ea/3Jig	c/sheet	Rework
			Dry	Dryer Dry Jig	Temperature Belt speed	refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework
			Baking	Baking Hole mesh net	Temperature Belt speed	refer to Guide Sheet	1/week	Parameter C/Sheet	Breakage Pollution	refer to Guide Sheet	Visual Inspection	all	Lot card	Exhaust Rework
AG PASTE		q	TOP rinting	Printer screen	Squeeze velocity/presure SNAP	refer to Guide Sheet	1/day	-	PATTERN dimension	refer to Guide Sheet	measure	10ea/3Jig	c/sheet	Rework
			Dry	Dryer Dry Jig	Temperature Belt speed	refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework
AG PASTE			BOTTOM PAD rinting	printer screen	Squeeze velocity/presure SNAP	refer to Guide Sheet	1/day	-	PATTERN dimension aspect	refer to Guide Sheet	measure Microscope	10ea/3Jig	c/sheet	Rework

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Product			Issued	ued/Revision 04.04.06		Process Control			1	Record	By designed	By chec	cked By	approved	
CHIP ANTENNA			Revise						PRCP-		01				
Input	FLOW CHART		Process		M	Management of Factors				Management of quality					
Materials	prepar ation	Main Process	name	Equipment Name	Checked		Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action
			Dry	Dryer Dry Jig	Temperature Belt speed		refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework
			Baking	Baking Hole mesh net	Temperature Belt speed		refer to Guide Sheet	1/week	Parameter C/Sheet	Breakage Pollution	refer to Guide Sheet	Visual Inspection	all	Lot card	Exhaust Rework
		\Diamond	aspect inspection							aspect	Reference SPL refer to Guide Sheet	Visual Inspection microscope	all	Lot card	Exhaust repair
			MARKING	Marking Machine						marking	Reference SPL	Visual Inspection	all	Lot card production diary	Rework Exhaust
		\Diamond	Electrical Characteristic	NETWORK Inspection Jig	proofreading Condition		refer to Guide Sheet	1/2hour	C/sheet	Electrical Characteristic	refer to Guide Sheet	Network	all	Lot card production diary	Exhaust repair
		\Diamond	aspect inspection							aspect dimension	Reference SPL refer to Guide Sheet	Visual Inspection microscope	all	Lot card production diary	Exhaust repair
Carrier cover reel			Taping							Quantity Direction aspect	refer to Guide Sheet	Manua I	all	Lot card	Rework
		\Diamond	shipper inspection	NETWORK Inspection Jig	proofre Condi		refer to Guide Sheet	1/person	C/sheet	Electrical Characteristic aspect packing	refer to Guide Sheet	Network microscope Visual Inspection	refer to Guide Sheet	Result Paper	return Exhaust
packing box label			packing	bar code printer						packing P/N Quantity	refer to Guide Sheet	Visual Inspection	all	-	Rework
		\bigcirc	packing inspection							packing P/N Quantity	refer to Guide Sheet	Visual Inspection	all	_	return

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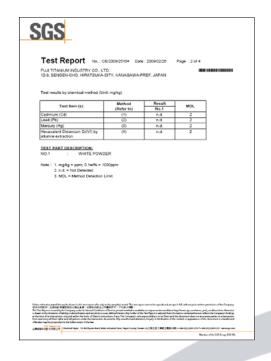


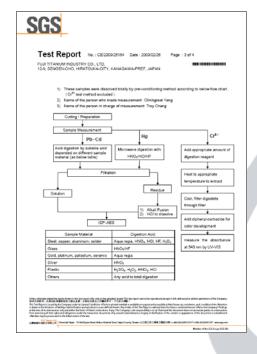
17. RoHS Data

17.1 Ceramic Powder

Parts Name	White Powder(MMS-08)				
Tester Organization	SGS Testing KOREA co. Ltd.				
Measurement Tester	Please see the 'method' in the test report				
Measurement Data	Please see the report under the table				









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17.2 Ag Paste

Parts Name	Silver Paste				
Tester Organization	SGS Testing KOREA co. Ltd.				
Measurement Tester	Please see the 'method' in the test report				
Measurement Data	Please see the report under the table				



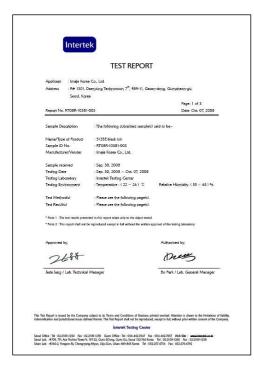


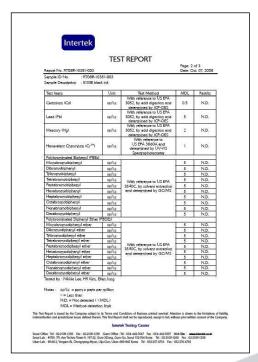
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17.3 Marking Ink(Black Ink)

Parts Name	Black Ink
Tester Organization	Intertek Testing Center
Measurement Tester	Please see the 'method' in the test report
Measurement Data	Please see the report under the table







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